



P- Channel Enhancement MOSFET



VDS= -30V, ID= -4.2A

DESCRIPTION

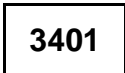
The YS3401 is the highest performance trench P-ch MOSFETs with extreme high cell density , which provide excellent RDS(on) and gate charge for most of the small power switching and load switch applications.

The YS3401 meet the RoHS and Green Product requirement with full function reliability approved.

FEATURES

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Green Device Available

MARKING



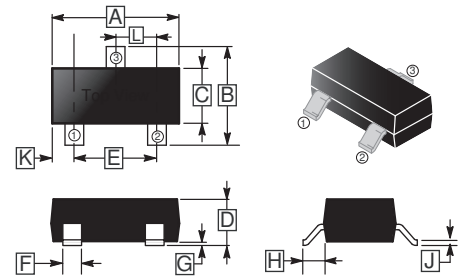
PACKAGE INFORMATION

Package	MPQ	Leader Size
SC-59	3K	7 inch

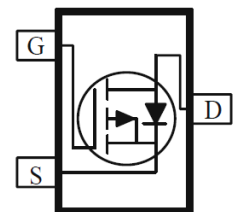
ORDER INFORMATION

Part Number	Type
YS3401	Lead (Pb)-free and Halogen-free

SC-59



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.70	3.10	G	0.10	REF.
B	2.10	3.00	H	0.40	REF.
C	1.20	1.70	J	0.047	0.207
D	0.89	1.40	K	0.5	REF.
E	2.00	Typ.	L	0.95	REF.
F	0.30	0.50			



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ratings		Unit	
		≤10sec	Steady State		
Drain-Source Voltage	V _{DS}	-30		V	
Gate-Source Voltage	V _{GS}	±12		V	
Continuous Drain Current ¹ @V _{GS} = -10V	I _D	T _A =25°C	-4.2	-3.7	A
		T _A =70°C	-3.5	-3	
Pulsed Drain Current ³	I _{DM}	-30		A	
Power Dissipation	P _D	T _A =25°C	1.4		W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~150		°C	
Thermal Resistance Rating					
Thermal Resistance Junction-ambient ¹	R _{θJA}	≤10sec, 90		°C/W	
		Steady State, 125			
Thermal Resistance Junction-ambient ²		270			
Thermal Resistance Junction-case ¹	R _{θJC}	80			

YS3401

ELECTRICAL CHARACTERISTICS (T_J=25°C unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
Drain-Source Breakdown Voltage	BV _{DSS}	-30	-	-	V	V _{GS} =0, I _D = -250uA	
Gate-Threshold Voltage	V _{GS(th)}	-0.6	-	-1.3	V	V _{DS} =V _{GS} , I _D = -250uA	
Forward Transconductance	g _{fs}	-	5.6	-	S	V _{DS} = -5V, I _D = -3A	
Gate-Body Leakage Current	I _{GSS}	-	-	±100	nA	V _{GS} = ±12V	
Drain-Source Leakage Current	T _J =25°C	I _{DSS}	-	-	-1	µA	V _{DS} = -24V, V _{GS} =0
	T _J =55°C		-	-	-5		V _{DS} = -24V, V _{GS} =0
Drain-Source On-Resistance ⁴	R _{DS(ON)}	-	-	50	mΩ	V _{GS} = -10V, I _D = -4.2A	
		-	-	65		V _{GS} = -4.5V, I _D = -4A	
		-	-	90		V _{GS} = -2.5V, I _D = -1A	
Total Gate Charge	Q _g	-	11.9	-	nC	V _{DS} = -15V V _{GS} = -4.5V I _D = -3A	
Gate-Source Charge	Q _{gs}	-	1.8	-			
Gate-Drain ("Miller") Charge	Q _{gd}	-	3	-			
Turn-on Delay Time	T _{d(on)}	-	6.6	-	nS	V _{DD} = -15V V _{GS} = -4.5V I _D = -3 R _G =3.3Ω R _L =5Ω	
Rise Time	T _r	-	27.8	-			
Turn-off Delay Time	T _{d(off)}	-	46.2	-			
Fall Time	T _f	-	20.6	-			
Input Capacitance	C _{iss}	-	920	-	pF	V _{GS} =0 V _{DS} = -15V f=1.0MHz	
Output Capacitance	C _{oss}	-	73	-			
Reverse Transfer Capacitance	C _{rss}	-	71	-			
Source-Drain Diode							
Diode Forward Voltage ⁴	V _{SD}	-	-	-1.2	V	I _S = -1A, V _{GS} =0	
Continuous Source Current ¹	I _S	-	-	-3.7	A		
Pulsed Source Current ³	I _{SM}	-	-	-15	A		

Notes:

1. Surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. When mounted on Min. copper pad.
3. Pulse width limited by maximum junction temperature.
4. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.

DEVICE CHARACTERISTICS

YS3401

CHARACTERISTIC CURVES

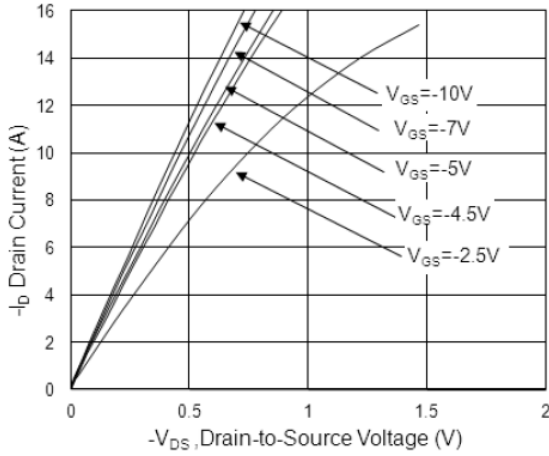


Fig.1 Typical Output Characteristics

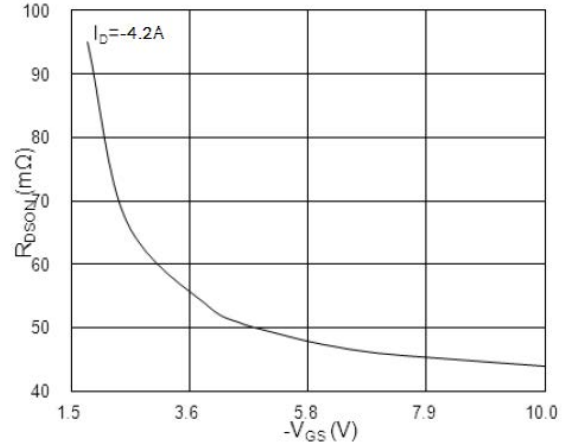


Fig.2 On-Resistance vs. G-S Voltage

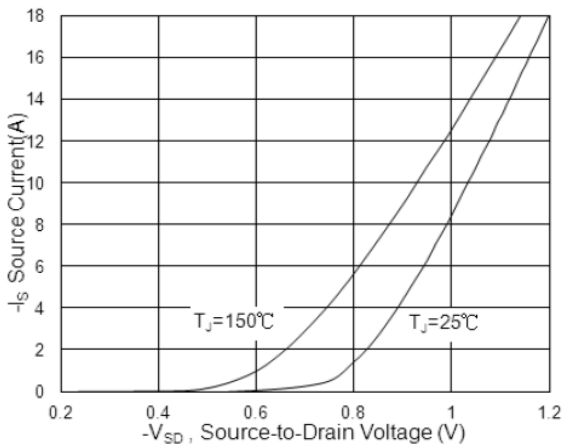


Fig.3 Forward Characteristics Of Reverse

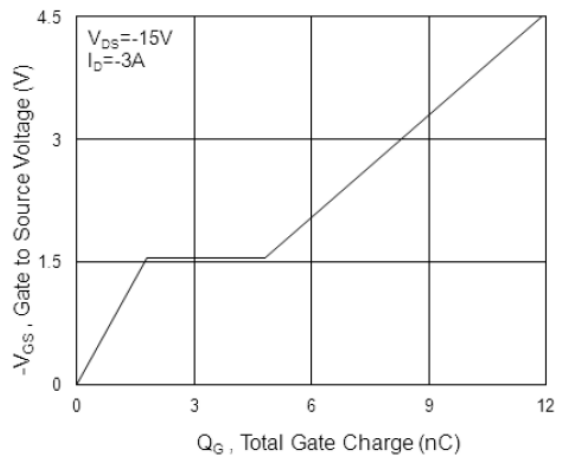


Fig.4 Gate-Charge Characteristics

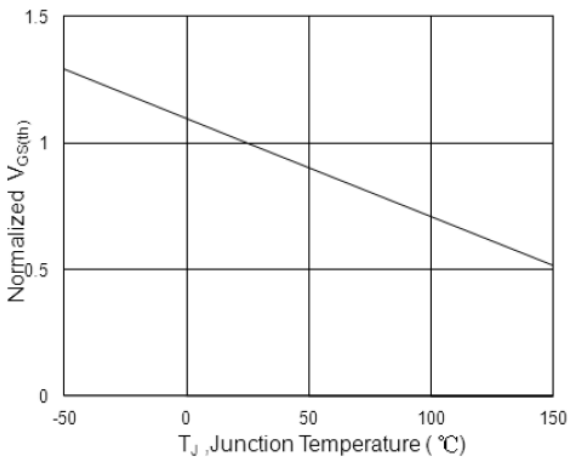


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

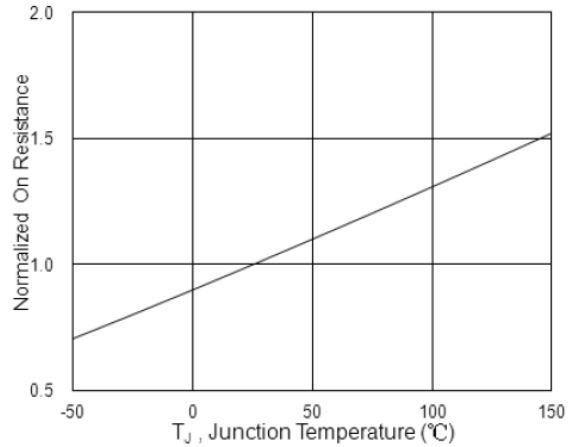


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

DEVICE CHARACTERISTICS

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CHARACTERISTIC CURVES

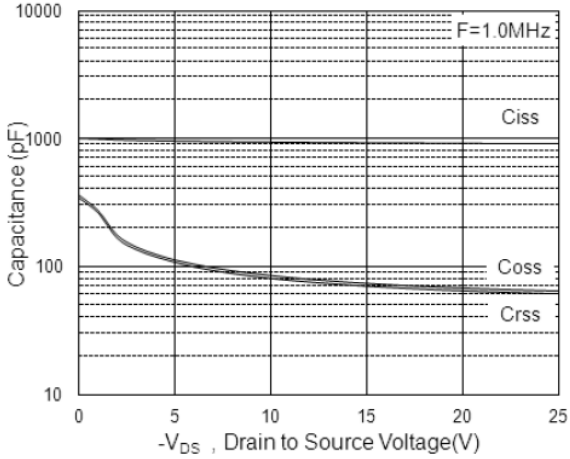


Fig.7 Capacitance

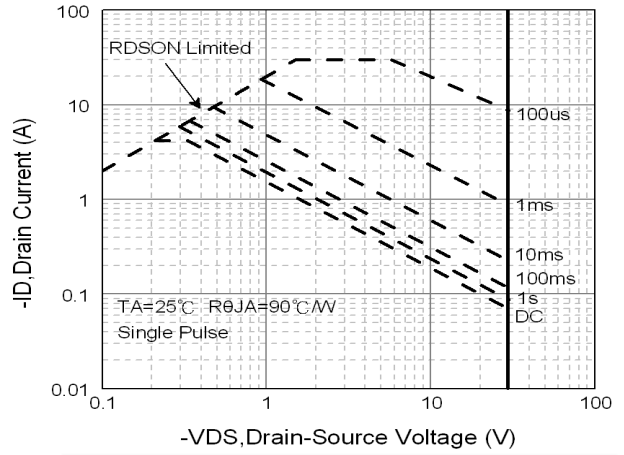


Fig.8 Safe Operating Area

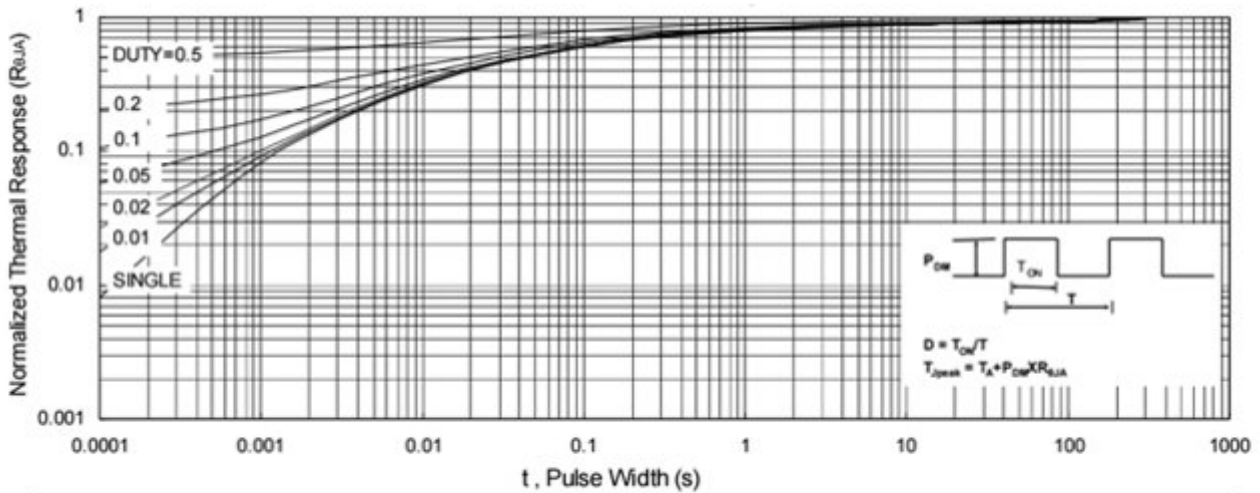


Fig.9 Normalized Maximum Transient Thermal Impedance

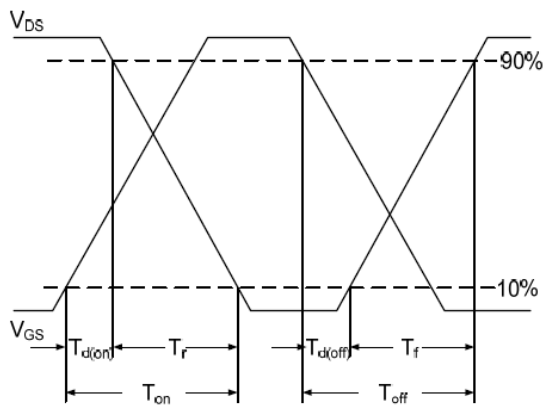


Fig.10 Switching Time Waveform

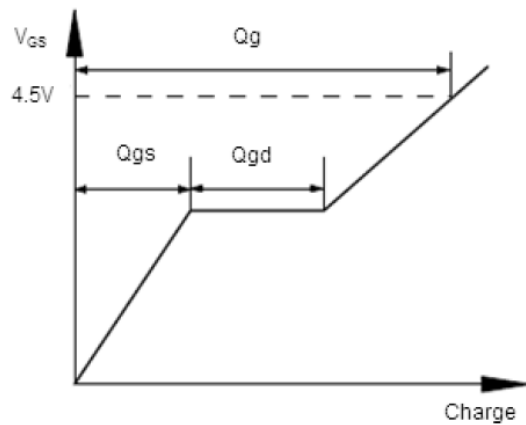


Fig.11 Gate Charge Waveform